RoHS Compliant SATA-Disk Module 3

22P/90D Specification

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Version 1.2



Apacer Technology Inc.

4th FI., 75 Xintai 5th Rd., Sec.1, Hsichih, New Taipei City, Taiwan 221 Tel: +886-2-2698-2888 Fax: +886-2-2698-2889 www.apacer.com



Features:

- Standard Serial ATA 2.6 (Gen. 2)
 - Serial ATA 2.6 (Gen. 2)
 - SATA II, 3.0 Gbps
 - ATA-compatible command set
- Capacities
 - 1, 2, 4, 8, 16 GB

• Performance*

- Burst read/write: 300 MB/sec
- Sustained read: up to 115 MB/sec
- Sustained write: up to 90 MB/sec

• Intelligent endurance design

- Built-in hardware ECC, enabling up to 14/28 bit correction per 1K bytes
- Static wear-leveling scheme together with dynamical block allocation to significantly increase the lifetime of a flash device and optimize the disk performance
- Flash bad-block management
- S.M.A.R.T.
- Power Failure Management
- ATA Secure Erase
- Trim
- NAND Flash Type: SLC

*Varies from capacities.

- Data integrity under power-cycling
 No battery required for data storage
- Temperature ranges
 - Operation:
 - Standard: 0°C to 70°C Extended Temperature: -40°C to 85°C
 - Storage: -40℃ to 100℃
 - Supply voltage
 - 5.0 V ± 5%
- Low power consumption*
 - Active mode: 357mA@5.0 V
 - Idle mode: 89 mA@5.0 V
- Connector type
 - 7-pin signal connector
 - 15-pin power connector
- RoHS Compliant



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1. Product Description

1.1 Introduction

Apacer's SATA Disk Module (SDM) is a solid-state drive (SSD) that contains a controller, embedded firmware, and flash media along with a male connector. Using NAND flash memory devices, SDM interfaces with the host allowing data to be seamlessly transferred between the host and the flash devices.

SDM is designed with a single-chip controller, offering capacities of up to 16 gigabytes and providing full support for the SATA II high-speed interface standard. It can operate at sustained access rates of up to thirty five megabytes per second, which is much faster than any other competitor in the market.

In addition to buffer management through dynamical allocation, SDM adopts the static wear-leveling scheme to allow uniform use of all storage blocks, ensuring that the lifetime of a flash media can be significantly increased and the disk performance is optimized as well. SDM provides the S.M.A.R.T. feature complies with the SATA Rev. 2.6, ATA/ATAPI-7 specifications and uses the standard SMART command B0h to read data from the drive. This feature protects the user from unscheduled downtime by monitoring and storing critical drive performance.

1.2 Functional Block Diagram

SDM includes a single-chip SATA II controller and the flash media, as well as the SATA standard interface. The controller integrates the flash management unit with the controller itself to support multi-channel, multi-bank flash arrays. Figure 1-1 shows the functional block diagram.

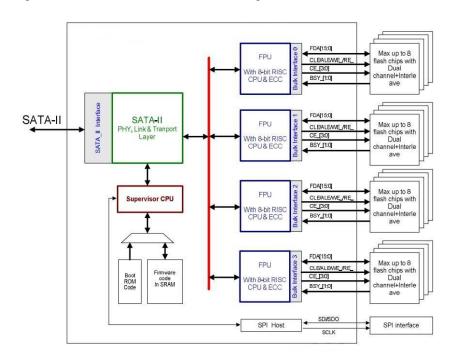


Figure 1-1 Apacer SDM block diagram



1.3 ATA Mode Support

SDM provides ATA mode support as follows:

- Up to PIO mode-4
- Up to Multiword DMA mode-2
- Up to UDMA mode-5

1.4 Capacity Specification

Capacity specification of SDM product family is available as shown in Table 1-1. It lists the specific capacity, the default numbers of logical cylinders and heads, and the number of logical sectors per track for each product line.

| Capacity | Total Bytes | Cylinders | Heads | Sectors | Max LBA |
|----------|----------------|-----------|-------|---------|------------|
| 1 GB | 988,839,936 | 1916 | 16 | 63 | 1,931,328 |
| 2 GB | 1,982,324,736 | 3841 | 16 | 63 | 3,871,728 |
| 4 GB | 3,952,263,168 | 7658 | 16 | 63 | 7,719,264 |
| 8 GB | 7,913,816,064 | 15334 | 16 | 63 | 15,456,672 |
| 16 GB | 15,842,017,280 | 16383 | 16 | 63 | 30,941,440 |

| Table 1-1 | Capacity s | pecification |
|-----------|------------|--------------|
|-----------|------------|--------------|

*Display of total bytes varies from file systems.

**Cylinders, heads or sectors are not applicable for these capacities. Only LBA addressing applies.

1.5 Performances

Performances of SDM are shown in Table 1-2a & Table 1-2b.

Table 1-2a Performance specification (Standard Speed)

| Capacity Performance | 1 GB | 2 GB | 4 GB | 8 GB |
|---------------------------|------|------|------|------|
| Sustained Read (MB/s) | 50 | 55 | 55 | 55 |
| Sustained Write (MB/s) | 16 | 24 | 45 | 45 |

Table 1-2b Performance specification (High Speed)

| Capacity Performance | 4 GB | 8 GB | 16 GB |
|---------------------------|------|------|-------|
| Sustained Read (MB/s) | 115 | 115 | 115 |
| Sustained Write (MB/s) | 46 | 90 | 90 |

Note: Performance varies from flash configurations.

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1.6 Pin Assignments

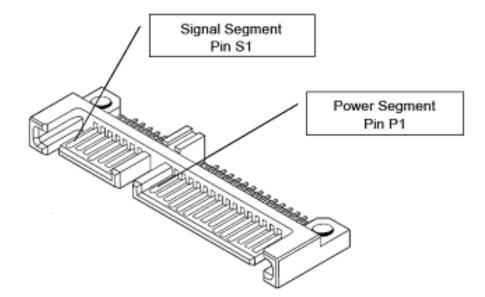


 Table 1-3 Signal segment

| Name | Туре | Description |
|------|------|--------------------------------|
| S1 | GND | |
| S2 | RxP | + Differential Receive Signal |
| S3 | RxN | - Differential Receive Signal |
| S4 | GND | |
| S5 | TxN | - Differential Transmit Signal |
| S6 | ТхР | + Differential Transmit Signal |
| S7 | GND | |

Table 1-4 Power segment

| Dia | Cirrael/Decerintica |
|-----|---------------------|
| Pin | Signal/Description |
| P1 | Not used (3.3V) |
| P2 | Not used (3.3V) |
| P3 | Not used (3.3V) |
| P4 | Ground |
| P5 | Ground |
| P6 | Ground |
| P7 | 5V |
| P8 | 5V |
| P9 | 5V |
| P10 | Ground |
| P11 | Reserved/Ground |
| P12 | Ground |
| P13 | Not used (12V) |
| P14 | Not used (12V) |
| P15 | Not used (12V) |



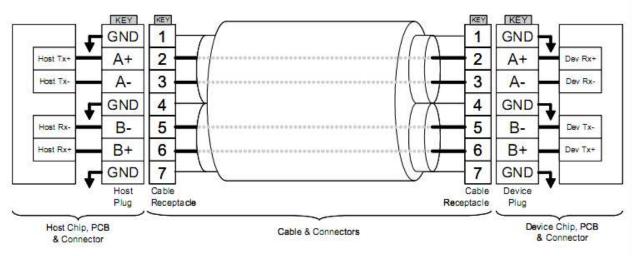


Figure 1-2 SATA Cable / Connector Connection Diagram

The connector on the left represents the Host with TX/RX differential pairs connected to a cable while the connector on the right shows the Device with TX/RX differential pairs also connected to the cable. Notice also the ground path connecting the shielding of the cable to the Cable Receptacle.



2. Software Interface

2.1 Command Set

Table 2-1 summarizes the ATA commands supported by SDM.

| Code | Command | Code | Command |
|------|------------------------------|------|------------------------|
| E5h | Check Power Mode | F3h | Security Erase Prepare |
| 06h | Data Set Management | F4h | Security Erase Unit |
| 90h | Execute Device Diagnostic | F5h | Security Freeze Lock |
| E7h | Flush Cache | F1h | Security Set Password |
| EAh | Flush Cache EXT | F2h | Security Unlock |
| ECh | Identify Device | 70h | Seek |
| E3h | Idle | EFh | Set Features |
| E1h | Idle Immediate | C6h | Set Multiple Mode |
| 91h | Initialize Device Parameters | E6h | Sleep |
| C8h | Read DMA | B0h | SMART |
| 25h | Read DMA EXT | E2h | Standby |
| C4h | Read Multiple | E0h | Standby Immediate |
| 29h | Read Multiple EXT | CAh | Write DMA |
| 20h | Read Sector | 35h | Write DMA EXT |
| 24h | Read Sector EXT | C5h | Write Multiple |
| 40h | Read Verify Sectors | 39h | Write Multiple EXT |
| 42h | Read Verify Sectors EXT | 30h | Write Sector |
| 10h | Recalibrate | 34h | Write Sector EXT |
| F6h | Security Disable Password | | |

Table 2-1 Command Set



3. Flash Management

3.1 Error Correction/Detection

SDM implements a hardware ECC scheme, based on the BCH algorithm. It can detect and correct up to 14 bits or 28 bits error in 1K bytes.

3.2 Bad Block Management

Although bad blocks on the flash media are already identified by the flash manufacturer, they can also be accumulated over time during operation. SDM's controller maintains a table that lists those normal blocks with disk data, the free blocks for wear leveling, and bad blocks with errors. When a normal block is detected broken, it is replaced with a free block and listed as a bad block. When a free block is detected broken, it is then removed from the free block list and marked as a bad block.

During device operation, this ensures that newly accumulated bad blocks are transparent to the host. The device will stop file write service once there are only two free blocks left such that the read function is still available for copying the files from the disk into another.

3.3 Wear Leveling

The NAND flash devices are limited by a certain number of write cycles. When using a FAT-based file system, frequent FAT table updates are required. If some area on the flash wears out faster than others, it would significantly reduce the lifetime of the whole SSD, even if the erase counts of others are far from the write cycle limit. Thus, if the write cycles can be distributed evenly across the media, the lifetime of the media can be prolonged significantly. This scheme is called wear leveling.

Apacer's wear-leveling scheme is achieved both via buffer management and Apacer-specific static wear leveling. They both ensure that the lifetime of the flash media can be increased, and the disk access performance is optimized as well.

3.4 Power Failure Management

The Low Power Detection on the controller initiates crucial data saving before the power supplied to the device is too low. This feature prevents the device from crash and ensures data integrity during an unexpected power-off.

3.5 ATA Secure Erase

Accomplished by the Secure Erase (SE) command, which added to the open ANSI standards that control disk drives, "ATA Secure Erase" is built into the disk drive itself and thus far less susceptible to malicious software attacks than external software utilities. It is a positive easy-to-use data destroy command, amounting to electronic data shredding. Executing the command causes a drive to internally completely erase all possible user data. This command is carried out within disk drives, so no additional software is required. Once executed, neither data nor the erase counter on the device would be recoverable, which blurs the accuracy of device lifespan. The process to erase will not be stopped until finished while encountering power failure, and will be continued when power is back on.



3.6 S.M.A.R.T.

S.M.A.R.T. is an acronym for Self-Monitoring, Analysis and Reporting Technology, an open standard allowing disk drives to automatically monitor their own health and report potential problems. It protects the user from unscheduled downtime by monitoring and storing critical drive performance and calibration parameters. Ideally, this should allow taking proactive actions to prevent impending drive failure.

Apacer SDM uses the standard SMART command B0h to read data from the drive for SMART feature as the SATA Rev.2.6 ATA/ATAPI-7 specifications. Based on the SFF-8035i Rev. 2.0 specifications, Apacer SMART defines vendor-specified SMART Attribute IDs (A0h, A1h, A2h, A3h, A4h-A5h) in SDM. They represent initial back block count, bad block count, spare block count, maximum erase count, and average erase counts respectively. When the Apacer SMART Utility running on the host, it analyzes and reports the disk status to the host before SDM is in critical condition.

3.7 Trim

Made of millions of NAND flash cells, SSD can be written into groups called pages in 4K size generally, but can only be erased in larger groups called blocks of 128 pages or 512KB. These stipulations are partially the source of many performance issues. Until an address gets used again, the SSD has to keep track of every last bit of data that's written on it. The ATA-Trim instruction tilts the balance in favor of the SSD. Trim addresses a major part of the performance degradation issue over time that plagues all SSDs. A Trim enabled drive running an OS with Trim supported will stay closer to its peak performance over time.



4. Environmental Specifications

Environmental specification of SDM3 product family which follows the MIL-STD-810F standards is available as shown in below table 4-1.

| Item | Specification |
|-------------------------|---|
| operating temp. | 0~70(°C) ^{*1} ;-40~85(°C) ^{*2} |
| non-operating temp. | -40~100(°C) |
| humidity | 10~95% R.H, 30(°C) max. wet bulb temp., operating |
| operating vibration | 10~2000(Hz), 15(G), sine wave |
| non-operating vibration | 20~2000(Hz), 7.7(Grms), random wave |
| operating shock | 50(G), 11(ms), half-sine wave |
| non-operating shock | 1500(G), 0.5(ms), half-sine wave |
| *1 : commorcial grada | |

Table 4-1 SDM3 environmental specifications

*1 : commercial grade

*2 : industrial grade

4.1 Mean Time Between Failures (MTBF)

Mean Time Between Failures (MTBF) is predicted based on reliability data for the individual components in SDM3. Although many component MTBFs are given in databases and often these values are not really accurate, the prediction result for SDM3 is more than 2,000,000 hours.

4.2 Certification and Compliance

SDM3 complies with the following standards:

- CE EN55022/55024
- FCC 47CFR Part15 Class B
- RoHS
- MIL-STD-810F
- SATA II (SATA Rev. 2.6)
- Up to ATA/ATAPI-7 (including S.M.A.R.T.)



5. Electrical Specification

Caution: Absolute Maximum Stress Ratings – (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.

| Range | Ambient Temperature | 5V |
|----------------------|---------------------|----------|
| Standard | 0℃ to +70℃ | |
| Extended Temperature | -40℃ to 85℃ | 4.5-5.5V |

| | Table 5-2: | Absolute | maximum | power p | in stress r | atings |
|--|------------|----------|---------|---------|-------------|--------|
|--|------------|----------|---------|---------|-------------|--------|

| Parameter | Symbol | Conditions |
|--|-----------------|-------------------------------|
| Input Power | V _{DD} | -0.3V min. to 6.5V max. |
| Voltage on any pin except V_{DD} with respect to GND | V | -0.5V min. to VDD + 0.5V max. |

Table 5-3: Recommended system power-up timings

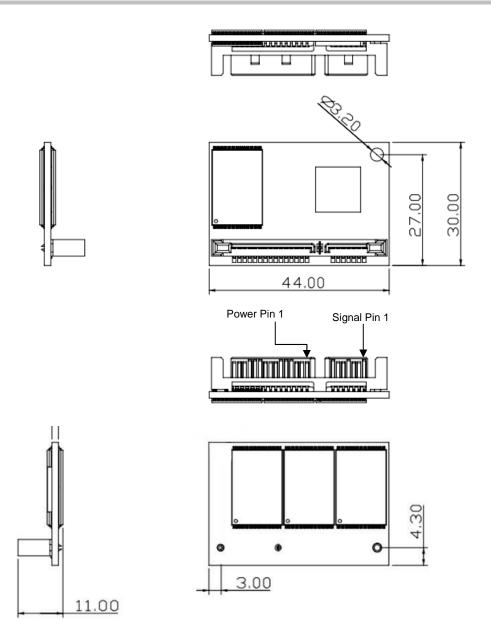
| Symbol | Parameter | Typical | Maximum | Units |
|------------------------------------|-----------------------------|---------|---------|-------|
| T _{PU-READY} ¹ | Power-up to Ready Operation | 200 | 1000 | ms |
| T _{PU-WRITE} ¹ | Power-up to Write Operation | 200 | 1000 | ms |

1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.



6. Physical Characteristics

6.1 Dimension



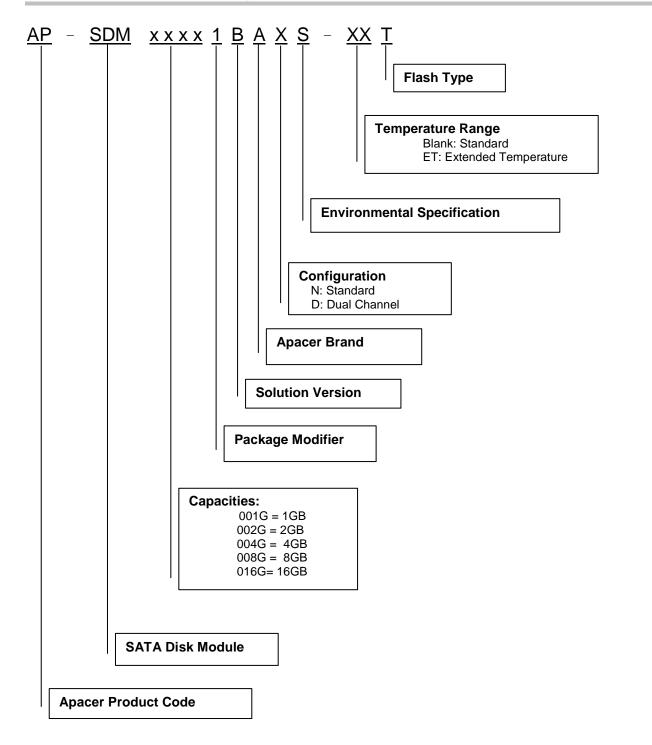
Unit: mm Tolerance: ± 0.25

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7. Product Ordering Information

7.1 **Product Code Designations**



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7.2 Valid Combinations

7.2.1 SDM3 22P/90D Standard type

| Capacity | Standard | Extended Temperature |
|----------|-------------------|----------------------|
| 1GB | AP-SDM001G1BANS-T | AP-SDM001G1BANS-ETT |
| 2GB | AP-SDM002G1BANS-T | AP-SDM002G1BANS-ETT |
| 4GB | AP-SDM004G1BANS-T | AP-SDM004G1BANS-ETT |
| 8GB | AP-SDM008G1BANS-T | AP-SDM008G1BANS-ETT |

7.2.2 SDM3 22P/90D High Speed type

| Capacity | Standard | Extended Temperature |
|----------|-------------------|----------------------|
| 4GB | AP-SDM004G1BADS-T | AP-SDM004G1BADS-ETT |
| 8GB | AP-SDM008G1BADS-T | AP-SDM008G1BADS-ETT |
| 16GB | AP-SDM016G1BADS-T | AP-SDM016G1BADS-ETT |

Note: Valid combinations are those products in mass production or will be in mass production. Consult your Apacer sales representative to confirm availability of valid combinations and to determine availability of new combinations.



Revision History

| Revision | Date | Description | Remark |
|----------|------------|-----------------------------------|--------|
| 1.0 | 2011/02/25 | Formal release | |
| 1.1 | 2011/04/01 | Updated Performance Specification | |
| 1.2 | 2011/06/23 | Updated Performance Specification | |



Global Presence

| Taiwan (Headquarters) | Apacer Technology Inc. 4 th FI, 75 Xintai 5 th Rd., Sec.1 Hsichih, New Taipei City Taiwan 221 R.O.C. Tel: +886-2-2698-2888 Fax: +886-2-2698-2889 amtsales@apacer.com |
|-----------------------|---|
| U.S.A. | Apacer Memory America, Inc. 386 Fairview Way, Suite102, Milpitas, CA 95035 Tel: 1-408-518-8699 Fax: 1-408-935-9611 <u>sa@apacerus.com</u> |
| Japan | Apacer Technology Corp. 5F, Matsura Bldg., Shiba, Minato-Ku Tokyo, 105-0014, Japan Tel: 81-3-5419-2668 Fax: 81-3-5419-0018 ipservices@apacer.com |
| Europe | Apacer Technology B.V. Aziëlaan 22, 5232 BA 's-Hertogenbosch, The Netherlands Tel: 31-73-645-9620 Fax: 31-73-645-9629 sales@apacer.nl |
| China | Apacer Electronic (Shanghai) Co., Ltd 1301, No.251,Xiaomuqiao Road, Shanghai, 20032, China Tel: 86-21-5529-0222 Fax: 86-21-5206-6939 sales@apacer.com.cn |
| India | Apacer Technologies Pvt Ltd, #1064, 1st Floor, 7th 'A' Main, 3rd Block Koramangala, Bangalore – 560 034 Tel: +91 80 4152 9061/62/63 Fax: +91 80 4170 0215 sales india@apacer.com |